# 2SC2377

## Silicon NPN epitaxial planar type

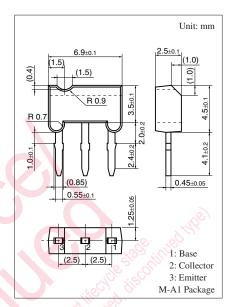
### For high-frequency amplification

#### ■ Features

- Optimum for RF amplification of FM/AM radios
- High transition frequency f<sub>T</sub>
- M type package allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	30	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	20	V	
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	3	V	
Collector current	$I_C$	15	mA	
Collector power dissipation	P <sub>C</sub>	200	mW	
Junction temperature	T <sub>j</sub>	150	°C	
Storage temperature	$T_{stg}$	-55 to +150	°C	



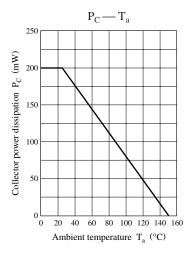
### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

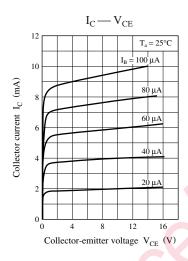
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Base-emitter voltage	V <sub>BE</sub>	$V_{CB} = 6 \text{ V}, I_{E} = -1 \text{ mA}$		720		mV
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 10 \text{ V}, I_E = 0$			100	nA
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = 20 \text{ V}, I_{B} = 0$			10	μΑ
Emitter-base cutoff current (Collector open)	I <sub>EBO</sub>	$V_{EB} = 3 \text{ V}, I_C = 0$			1	μΑ
Forward current transfer ratio *	h <sub>FE</sub>	$V_{CB} = 6 \text{ V}, I_{E} = -1 \text{ mA}$	65		260	_
Transition frequency	$f_T$	$V_{CB} = 6 \text{ V}, I_E = -1 \text{ mA}, f = 100 \text{ MHz}$	450	650		MHz
Noise figure	NF	$V_{CB} = 6 \text{ V}, I_E = -1 \text{ mA}, f = 100 \text{ MHz}$		3.3	5.0	dB
Power gain	$G_{P}$	$V_{CB} = 6 \text{ V}, I_E = -1 \text{ mA}, f = 100 \text{ MHz}$	20	24		dB
Reverse transfer capacitance (Common emitter)	C <sub>re</sub>	$V_{CB} = 6 \text{ V}, I_E = -1 \text{ mA}, f = 10.7 \text{ MHz}$		0.8	1.0	pF

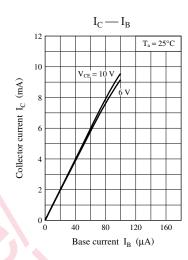
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

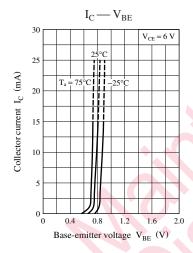
#### 2. \*: Rank classification

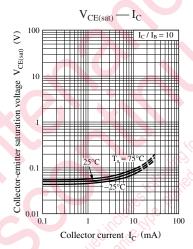
Rank	С	D
$h_{FE}$	65 to 160	100 to 260

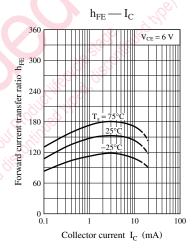


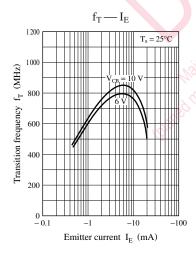


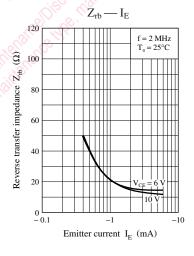


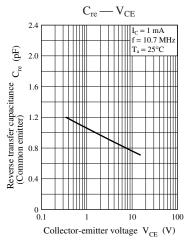


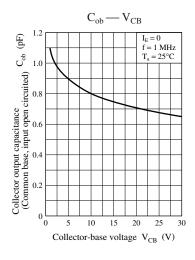


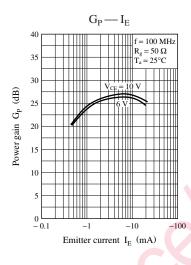


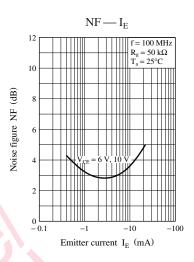


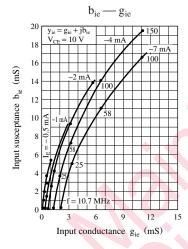


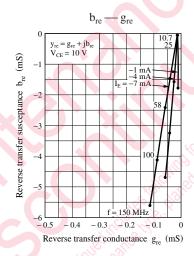


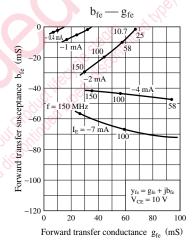


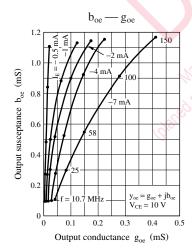












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